

ANALOG CONTROLLED VARIABLE GAIN AMPLIFIER

Package: MCM, 7mm x7mm



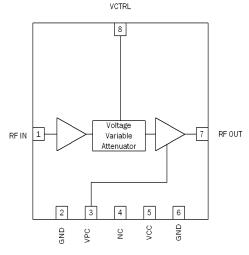


Features

- 1750 MHz to 2250 MHz Operation
- Gain=24dB Typical
- Gain Adjustment Range > 19dB
- ACPR≥-66dBc Typ. at +12dBm P_{OUT} (Dual Carrier WCDMA)
- Small 7 mmx7 mm, Multi-Chip Module

Applications

- Cellular, 3G Infrastructure
- WiBro, WiMax, LTE
- Microwave Radio
- High Linearity Power Control



Functional Block Diagram

Product Description

RFMD's RVA2007L is a fully integrated analog controlled variable gain amplifier featuring exceptional linearity over a greater than 19dB gain control range. This variable gain amplifier is controlled by a single 0V to 3.3V positive supply voltage. The RVA2007L is packaged in a small 7 mmx7 mm leadless laminate MCM which contains thermal vias for ultra low thermal resistance. This module is internally matched to $50\,\Omega$ and is easy to use with no external matching components required.

Ordering Information

RVA2007LSQ Sample bag with 25 pieces
RVA2007LSR 7" Sample reel with 100 pieces
RVA2007LTR7 7" Reel with 1500 pieces
RVA2007LTR13 13" Reel with 2500 pieces

RVA2007LPCK-410 1750 MHz to 2250 MHz PCBA with 5-piece sample bag

Optimum Technology Matching® Applied

☐ GaAs HBT	☐ SiGe BiCMOS	✓ GaAs pHEMT	☐ GaN HEM
☐ GaAs MESFET ✓ InGaP HBT	☐ Si BiCMOS	☐ Si CMOS	☐ RF MEMS
▼ InGaP HBT	☐ SiGe HBT	☐ Si BJT	☐ LDMOS



Absolute Maximum Ratings

Parameter	Rating	Unit
Max Device Current	770	mA
Max Device Voltage	5.5	V
Max Control Line Voltage	6	V
Max RF Input Power*	25	dBm
Max Junction Temp (T _J)	+150	°C
Max Storage Temp	+150	°C
Thermal Resistance (junction to backside of module)	14.8	°C/W
ESD	Class 1C (1000V min)	
Moisture Sensitivity Level	MSL3	

^{*}Load condition: $Z_L = 50\Omega$



Caution! ESD sensitive device.

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Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

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2002/95/EC.

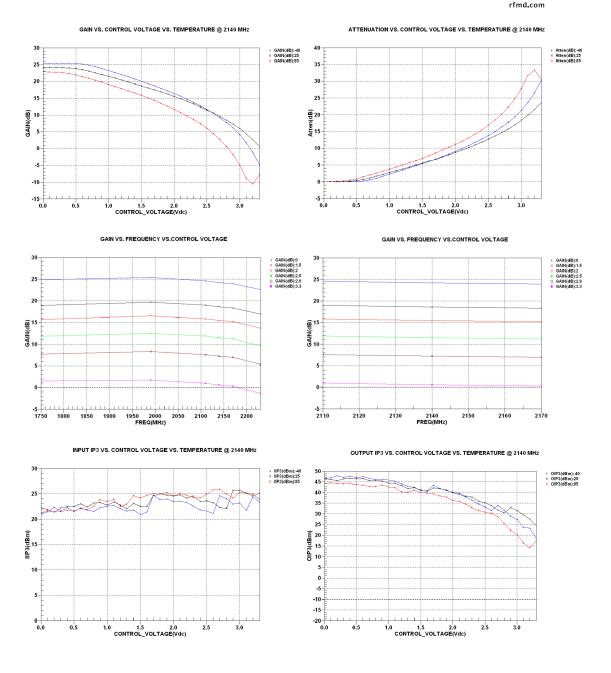
Parameter	Specification		Unit	Condition		
Farameter	Min.	Тур.	Max.	Unit	Condition	
					All specifications for -40 °C to +85 °C, 4.75 V to 5.25 V, and process variations unless otherwise stated.	
Frequency	2110		2170	MHz		
Temperature Range	-40	25	85	°C	Operating Range	
Gain	23	24.5	25.5	dB	Min attenuator setting, 5V, 25C	
Gain	22	24.5	26.5	dB	Over All Conditions	
Nominal Operating Output Power		12		dBm	Operating power for ACPR rating	
Output IP3	42	45		dBm	In high gain setting	
P1dB	28	29.5		dBm	Max gain setting	
ACPR	-60	-66		dBc	Dual carrier WCDMA, 7.5dB CF at nominal operating power; over full attenuation range	
Gain Flatness		0.2	0.6	dB	Over 50 MHz BW	
Gain Adjustment Range	19	23.5		dB		
Control Voltage Range	0		3.3	V		
Noise Figure		3.8	5.0	dB	Min attenuator setting	
Impedance		50		Ω		
Input Return Loss	15	20		dB	Over attenuation range	
Output Return Loss	14	15		dB	Over attenuation range	
Supply Voltage	4.75	5.0	5.25	V		
Supply Current (VPC=0V)	300	460	600	mA	Max current at -40 °C	
Supply Current (VPC=0V)	120	126	140	mA	Output amplifier shutdown total current	





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Parameter	Min.	Тур.	Max.	Unit	Condition	
					All specifications for -40 °C to +85 °C, 4.75V to 5.25V, and process variations unless otherwise stated.	
Frequency	1750		2250	MHz		
Temperature Range	-40	25	85	°C	Operating Range	
Gain		24.5		dB	Over All Conditions	
Nominal Operating Output Power		12		dBm	Operating power for ACPR rating	
Output IP3		43		dBm	In high gain setting	
P1dB		29.5		dBm	Max gain setting	
ACPR		-66		dBc	Dual carrier WCDMA, 7.5dB CF at nominal operating power; over full attenuation range	
Gain Flatness		0.2		dB	Over 50 MHz BW	
Gain Adjustment Range		23.5		dB		
Control Voltage Range				V		
Noise Figure		3.8		dB	Min attenuator setting	
Impedance		50		Ω		
Input Return Loss		20		dB	Over attenuation range	
Output Return Loss		15		dB	Over attenuation range	

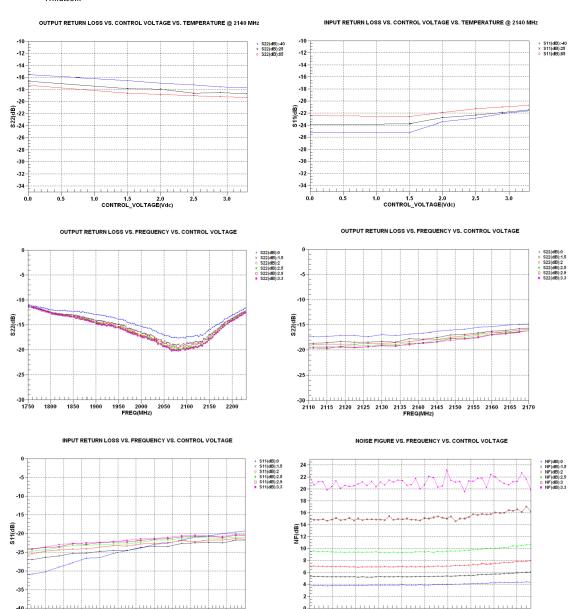








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1800 1850 1900

1950 2000 Freq(MHz) 2050

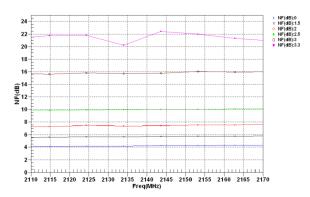
2100 2150

2200

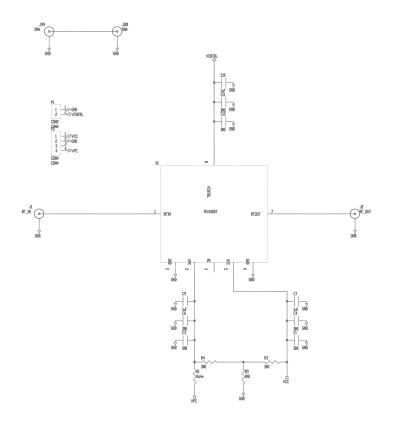
2110 2115 2120 2125 2130 2135 2140 2145 2150 2155 2160 2165 2170 FREQ(MHz)



NOISE FIGURE VS. FREQUENCY VS. CONTROL VOLTAGE



Evaluation Board Schematic





Evaluation Board Bill of Materials (BOM)

Description	Reference Designator	Manufacturer	Manufacturer's P/N
EVALUATION BOARD		DDI	RFVAx007L410(A)
CAP, 1μF, 10%, 10V, X5R, 0402	C7, C9-C10	MURATA ELECTRONICS	GRM155R61A105KE15D
RES, 0Ω, 0402	R1	KAMAYA, INC	RMC1/16SJPTH
CONN, SMA, END LAUNCH, UNIV, HYB MNT, FLT	J1-J2	HEILIND ELECTRONICS	PER MAT-21-1038
CONN, HDR, ST, PLRZD, 4-PIN, 0.100"	P2	ITW PANCON	MPSS100-4-C
CONN, HDR, ST, PLRZD, 2-PIN, 0.100"	P1	ITW PANCON	MPSS100-2-C
DNP	C1, C3-C4, C6, C11-C12, R3-R5		
RVA2007L MODULE	U1	RFMD	RVA2007L

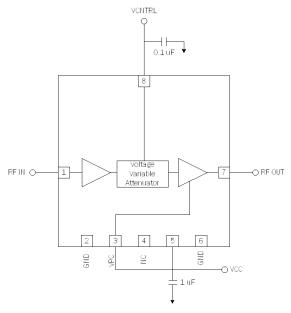
Pin Table and Description

Pin	Function	Description
1	RFIN	RF input pin. Internal DC block.
2	GND	Ground pin.
3	VPC	Power up/down control for 2nd stage amplifier. Apply V_{CC} to power on 2nd stage amplifier. Apply 0V to disable 2nd stage amplifier. Do not exceed V_{CC} +0.5V. Connect to V_{CC} if not needed. Decoupling capacitor may be desired on application board for control line noise.
4	NC	No connection.
5	VCC	Power supply for the module. Recommending 1uF decoupling cap on the application board.
6	GND	Ground pin.
7	RFOUT	RF output pin. Internal DC block.
8	VCTRL	Gain control voltage; 0V to 3.3V range. Maximum gain at 0V. Recommending 0.1uF decoupling on the application board.
Center Pad	GND	Center ground pads need to have a good thermal path on the application board. Use solder stencil pattern shown in the document to define solder paste during assembly.



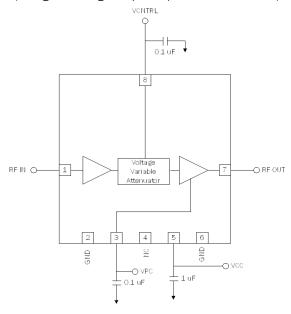
Application Schematic

(Without using final stage amplifier power down control)

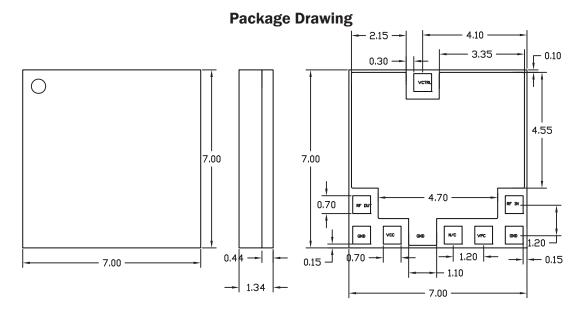


Application Schematic

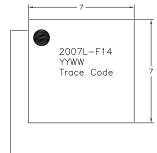
(Using final stage amplifier power down control)







Branding Diagram



Pin 1 Indicator

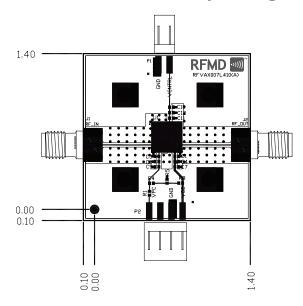
Fill in the YYWW Notation with the Date Code YY = Year

WW = Week

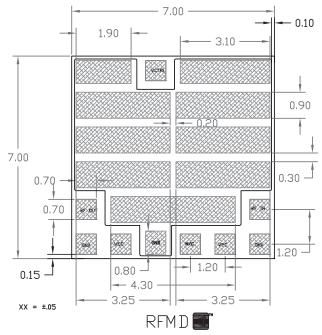
Trace Code to be assigned by SubCon



Evaluation Board Assembly Drawing



PCB Design Requirements



Note: This solder stencil pattern is required to prevent solder voiding that may impact thermal dissipation.